Ancillary ASIC - test preparations

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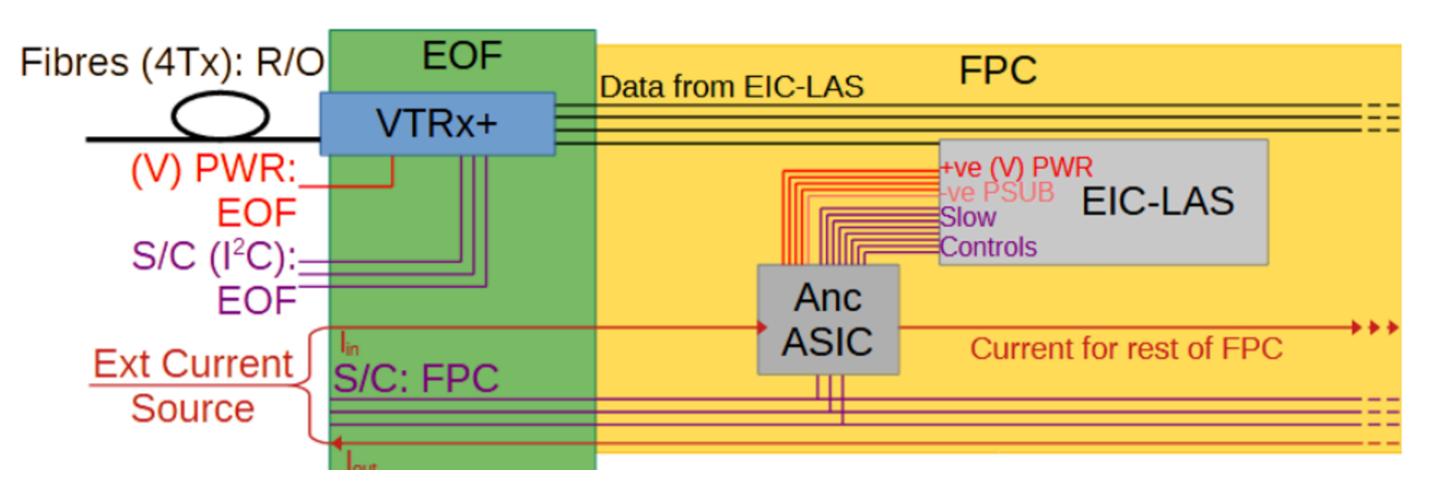
AncASIC

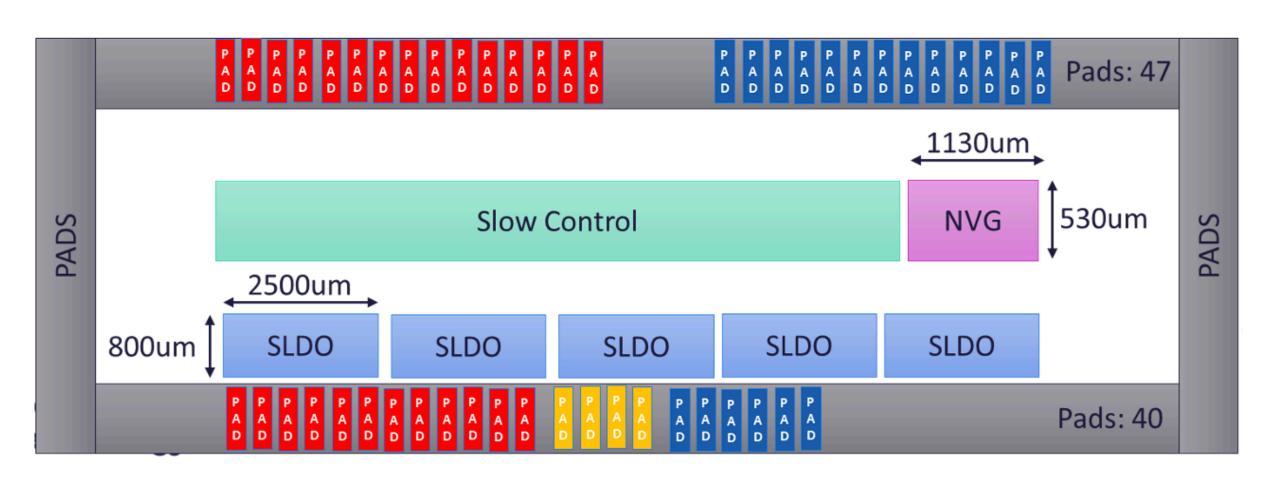
Main blocks:

- Negative Voltage Generator NVG
- SLDO
- Slow Control

(4) development stages (preliminary):

- MPW1, 2, 3, x prototype (chiplets)
- ER AncASIC production on 8" wafers





MPW1/MPW2

Main blocks MPW1:

- Negative Voltage Generator (NVG)
- SLDO Pre-Regulator
- CML Transceiver
- Transistor Test Structures (for radiation hardness validation of XT011 process)

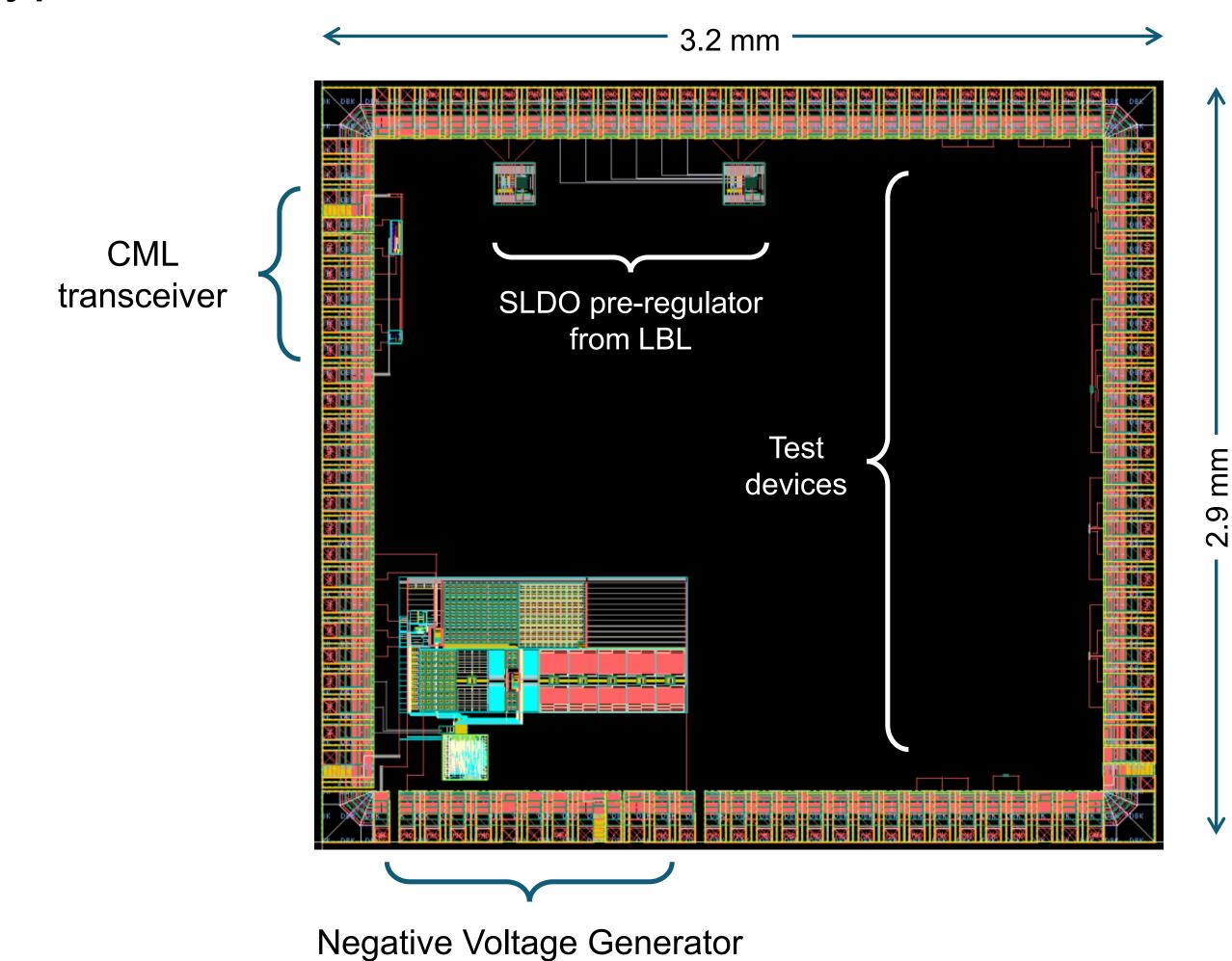
MPW2:

SLDO

Details:

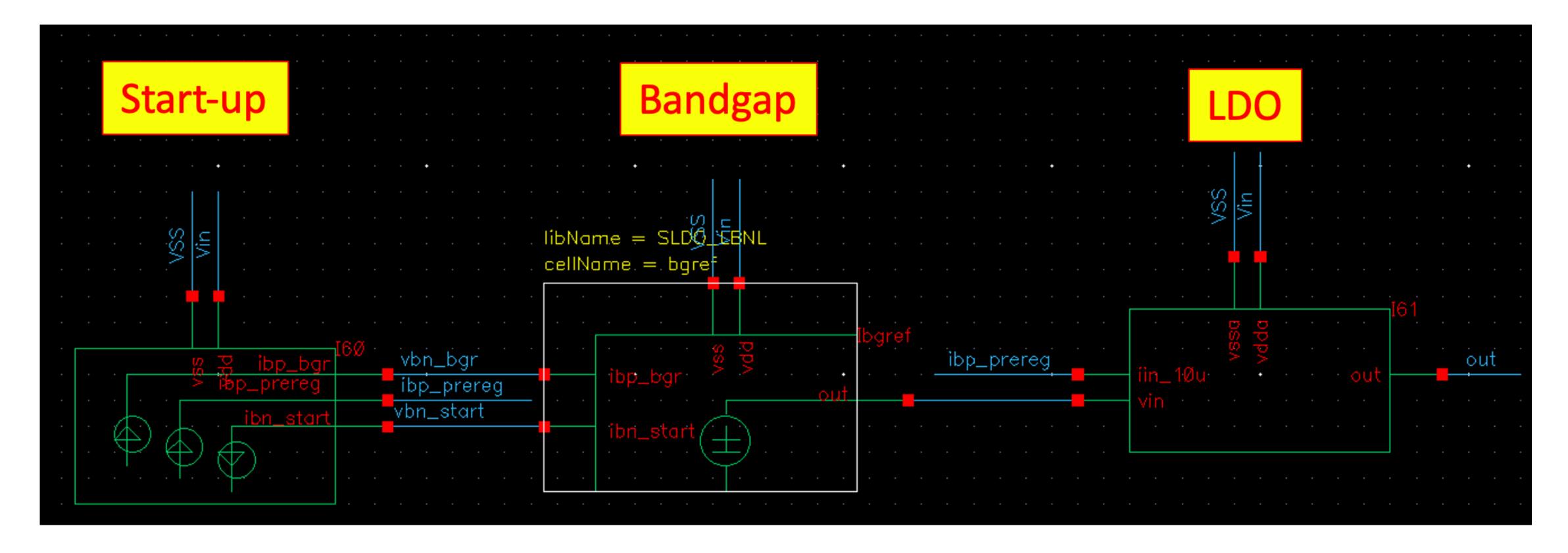
- 45 individual chipsets for each MPW
- Number of available pads = 110
- Submission is planned to May 2025
- Delivery from the fab in September 2025

1st Prototype: AncASIC sub-blocks and test devices



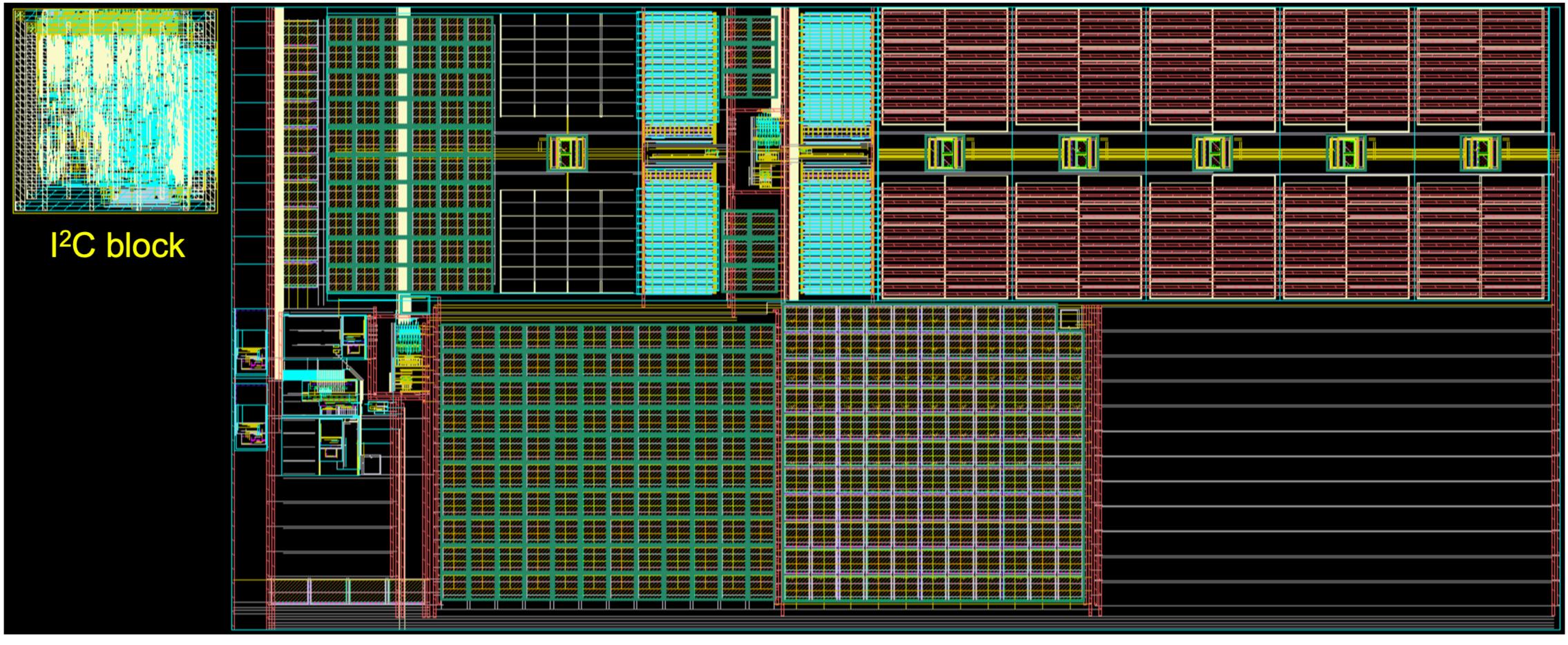


MPW1 - SLDO Pre-Regulator



- Power source
- Measure output and some internal signals

MPW1 - NVG



- Power source
- I²C control via FPGA
- Measure output voltage (default -3V)

MPW1 - Transistor Test Structures

- LVTs
- BJT
- MOSVC Capacitor
- Resistor
- Transistor charasteristics scan
- IV measurement
- LCR meter

- nelvt
 - W=1u, L=110n
 - W=1u, L=150n
 - W=1u, L=500n
 - W=1u, L=1u
- pelvt
 - W=1u, L=110n
 - W=1u, L=150n
 - W=1u, L=500n
 - W=1u, L=1u
- Brookhaven^{*}
 National Laboratory

- BJT
 - qpva
 - qpvb
- mosvc (7u x 7u cell)
- Rpp1 (w=3u and l=20u)
- nelvt, pelvt
 - Weff. = 100um, L=150nm
 - Interdigitation layout to measure leakage
 - Two copies
 - 1. minimum DTI enclosure spacing
 - 2. 1.0um DTI enclosure spacing

MPW1/MPW2 testing needs

- PCB carrier board
- Standard test equipment (power sources, IV, LCR meters, oscilloscope etc.)
- Transistor test structure IV setup
- Temperature chamber
- I²C FPGA control for NVG
- Irradiation (X-ray, Cobalt-60) TID up to 1MRad
- (SEE/SEU of I²C in a proton beam)

Testing details defined by WP1:

•https://docs.google.com/spreadsheets/d/1VWeK98f8jZUxhvNr1PAeVBIMx0neTcvY2W6wPgqrf0A/edit?usp=sharing

MPW1/MPW2 - Task list				
MPW1				
Task	Testing details, conditions	Comments	Equipment	
MPW1 tapeout/submission (WP1 task)				
MPW1 testing				
1 Test specs definition				
Carrier board PCB design + manufacturing, pre-testing				
3 Chip+PCB assembly, wirebonding				
4 SLDO Pre-Regulator characterization			Standard lab equipment (power supply, IV meters, oscilloscope etc.)	
Output Ripple/Noise	Load Capacitance - 1pF, 10pF, 100pf, 1nF	Number in red is the expected value. Others are for exploring the parameter space		
Transient Response (overshoot and settling time)	ESR - 3.5k			
PSRR and line regulation	Standard Temperature Range	-20, 27, 60, 105 C	Temperature chamber	
Start-up	Standard Radiation Range	0 - 1MRad in 100kRad steps		
	Ramp rate - 10u, 100u, 1m, 10m, 100m, 1s			
5 NVG characterization			Standard lab equipment (power supply, IV meters, oscilloscope etc. I2C control via FPGA	
Output Ripple/Noise	Load Capacitance - RANGE?			
Transient Response (overshoot and settling time)	Frequency - RANGE?			
PSRR and line regulation	Standard Temperature Range	-20, 27, 60, 105 C	Temperature chamber	
Start-up	Standard Radiation Range	0 - 1MRad in 100kRad steps		
	Standard Supply Variation	Plus and Minus 20%		
	Ramp Rate - RANGE?			
Test in combination with APTS/DPTS/ER1		Use NVG to generate back bias for already existing APTS and DPTS chips		
6 Transistor Test Structures characterization			Standard lab equipment (power supply, IV, LCR meters, oscilloscop	
lds vs Vgs			TTS characterization IV setup	
Vt extraction				
	Standard Temperature Range	-20, 27, 60, 105 C	Temperature chamber	
	Standard Radiation Range	0 - 1MRad in 100kRad steps		
	Standard Supply Variation	Plus and Minus 20%		
7 CML transciever				
8 Irradiation				
	X-rays Cobalt60	Chips powered during the irradiation, temperature monitoring		
	Standard Radiation Range	0 - 1MRad in 100kRad steps		
9 SEE/SEU Tests in a proton beam			Proton beam with XY table	

MPW3/MPWx

Main blocks:

- Negative Voltage Generator NVG
- SLDO
- Slow control

Details:

- 45 individual chipsets?
- Functionality and layout "identical" to the final AncASIC

Testing needs:

- PCB carrier board with connectors compatible with existing FPGA controls for slow control
- Probe card prototyping if pin-out changes are not expected
- Standard test equipment (power sources, IV meters, oscilloscope)
- Temperature chamber
- Slow control FPGA code
 - (Jo Schambach/ORNL works on MOSAIX emulator, BNL and LBNL AncASIC emulator slow control on FPGA)
- Irradiation (X-ray, Cobalt-60) TID up to 1MRad
- SEU/SEE tests of the sensitive digital circuits in a proton beam

	MPW3 - Task list		
MPW3			
Task	Testing details, conditions	Comments	Equipment
MPW3 tapeout/submission (WP1 task)			1
MPW3 testing			
im tro tosting			
1 Test specs definition			
Carrier board PCB design + manufacturing, pre-testing			
3 Chip+PCB assembly, wirebonding			
4 SLDO characterization			Standard lab equipment (power supply, IV meters, oscilloscope etc.)
Output Ripple/Noise	Load Capacitance - 1pF, 10pF, 100pf, 1nF	Number in red is the expected value. Others are for exploring the parameter space	
Transient Response (overshoot and settling time)	ESR - 3.5k		
PSRR and line regulation	Standard Temperature Range	-20, 27, 60, 105 C	Temperature chamber
Start-up	Standard Radiation Range	0 - 1MRad in 100kRad steps	
	Ramp rate - 10u, 100u, 1m, 10m, 100m, 1s		
5 NVG characterization			Standard lab equipment (power supply, IV meters, oscilloscope etc.)
Output Ripple/Noise	Load Capacitance - RANGE?		
Transient Response (overshoot and settling time)	Frequency - RANGE?		
PSRR and line regulation	Standard Temperature Range	-20, 27, 60, 105 C	Temperature chamber
Start-up	Standard Radiation Range	0 - 1MRad in 100kRad steps	
	Standard Supply Variation	Plus and Minus 20%	
	Ramp Rate - RANGE?		
Test in combination with APTS/DPTS/ER1		Use NVG to generate back bias for already existing APTS and DPTS chips	
6 Slow control characterization			Standard lab equipment (power supply, IV meters, oscilloscope etc.), Slow Control FPGA
7 Irradiation			
	X-rays Cobalt60	Chips powered during the irradiation, temperature monitoring	
	Standard Radiation Range	0 - 1MRad in 100kRad steps	
	SEU/SEU tests of digital circuits in a proton? beam		
8 SEE/SEU Tests in a proton beam			Proton beam with XY table

AncASIC production

Main blocks:

- Negative Voltage Generator NVG
- SLDO
- Slow control

Details:

- ER production on 8" wafers
- Production tested on wafer probing machine before dicing

Testing needs:

- Probe card design, manufacturing, pre-testing (might be developed already in the previous MPWx)
- Wafer probing HW/FW/SW control setup
 - could be used modification of MOSAIX/LAS setup, for the slow control FPGA code AncASIC emulator
- Production database for storing the test results (common DB used also for the sensor testing etc.)
- Wafer prober + physical testing of the production wafers

AncASIC - Task list

	AncASIC final
	Task
	AncASIC production (WP1 task)
	AncASIC testing
1	Test specs definition
2	Probe card design, manufacturing, pre-testing
3	Database for testing results
4	Wafer probing HW/FW/SW control setup
5	Production testing on wafer prober

Task List comments

Close collaboration with WP1 necessary to define test parameters and report the results back to AncASIC designers during prototyping.

Carrier board PCB design

Manufacturing of PCB for Carrier board Manufacturing of PCB for probe card

Pre-testing of carrier board and probe card

Slow control test setup:

- Assumption is that the readout and testing is done via FPGA based emulator system designe by BNL/LBNL
 - Any help needed?

General questions:

- Results analysis and performance definition
- DB structure needed to store the analysis results and general characterization
- Software integration needs to automatize testing procedures

Conclusion

The purpose of this presentation is to show the tasks that will need to be completed for prototype testing and production of AncASIC. The list of tasks and tests is not final, it will of course be revised and we would be happy to receive any input here.

We have preliminary applicants for some tasks, but most are available for volunteers from the SVT collaboration to join. We need to collect interest and people that can do the work. So please think about which tasks your group wants to participate in and let us know, because very soon it will be necessary to assign the responsibility for the tasks at least for MPW1/2.

At the same time as the assignment of tasks, it will be necessary to think how to divide chips from MPWs' into tasks/groups.